



Material Content Data Sheet



Sales Product Name		BTS7004-1EPP		Issued		13. August 2018			
MA#		MA002466218							
Package		PG-TSDSO-14-22		Weight*		65.28 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.355	2.08	2.08	20755	20755	
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		144		
	non noble metal	zinc	7440-66-6	0.038	0.06		578		
	non noble metal	iron	7439-89-6	0.754	1.16		11551		
wire	non noble metal	copper	7440-50-8	30.617	46.91	48.14	469006	481279	
	non noble metal	copper	7440-50-8	0.792	1.21	1.21	12137	12137	
	encapsulation	organic material	carbon black	1333-86-4	0.086	0.13		1324	
plating	plastics	epoxy resin	-	3.371	5.16		51638		
	inorganic material	silicondioxide	60676-86-0	25.354	38.84	44.13	388387	441349	
	leadfinish	non noble metal	tin	7440-31-5	1.642	2.51	2.51	25147	25147
glue	noble metal	silver	7440-22-4	0.816	1.25	1.25	12501	12501	
*deviation	< 10%	plastics	epoxy resin	-	0.078	0.12		1196	
		noble metal	silver	7440-22-4	0.368	0.56	0.68	5636	6832
Sum in total:						100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com